

N-Channel 30-V(D-S) MOSFET

Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)

GENERAL DESCRIPTION

The ME4626-G is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching , and low in-line power loss are needed in a very small outline surface mount package.

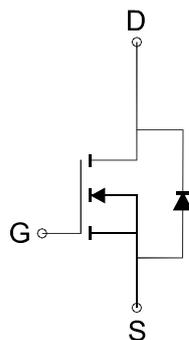
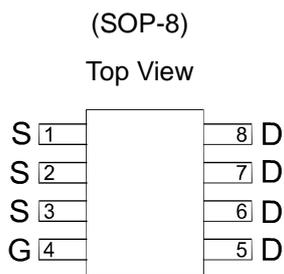
FEATURES

- $R_{DS(ON)} \leq 3.5m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} \leq 4.5m\Omega @ V_{GS}=4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

APPLICATIONS

- Power Management in Note book
- Battery Powered System
- DC/DC Converter
- Load Switch

PIN CONFIGURATION



N-Channel MOSFET

Ordering Information: ME4626 (Pb-free)

ME4626-G (Green product-Halogen free)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current($T_J = 150^\circ C$)*	I_D	$T_A = 25^\circ C$	21
		$T_A = 70^\circ C$	16.9
Pulsed Drain Current	I_{DM}	84	A
Maximum Power Dissipation*	P_D	$T_A = 25^\circ C$	2.5
		$T_A = 70^\circ C$	1.6
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Thermal Resistance-Junction to Ambient*	$R_{\theta JA}$	50	$^\circ C/W$
Thermal Resistance-Junction to Lead*	$R_{\theta JL}$	24	

* The device mounted on 1in² FR4 board with 2 oz copper



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Electrical Characteristics (TA=25°C Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V, ID=250 μA	30			V
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250 μA	1		3	V
IGSS	Gate Leakage Current	VDS=0V, VGS=±20V			±100	nA
IDSS	Zero Gate Voltage Drain Current	VDS=30V, VGS=0V			1	μA
RDS(ON)	Drain-Source On-State Resistance ^a	VGS=10V, ID= 15A		2.8	3.5	mΩ
		VGS=4.5V, ID= 10A		3.3	4.5	
VSD	Diode Forward Voltage	IS=15A, VGS=0V		0.8	1.2	V
DYNAMIC						
Qg	Total Gate Charge(4.5V)	VDS=15V, VGS=4.5V, ID=15A		62		nC
Qg	Total Gate Charge(10V)	VDS=15V, VGS=10V, ID=15A		128		
Qgs	Gate-Source Charge			18		
Qgd	Gate-Drain Charge			27		
Ciss	Input capacitance	VDS=15V, VGS=0V, f=1.0MHz		5730		pF
Coss	Output Capacitance			660		
Crss	Reverse Transfer Capacitance			220		
Rg	Gate-Resistance	VDS=0V, VGS=0V, f=1MHz		0.9		Ω
td(on)	Turn-On Delay Time	VDD=15V, RL =15Ω ID=1A, VGEN=10V RG=6Ω		33		ns
tr	Turn-On Rise Time			20		
td(off)	Turn-Off Delay Time			110		
tf	Turn-Off Fall Time			17		

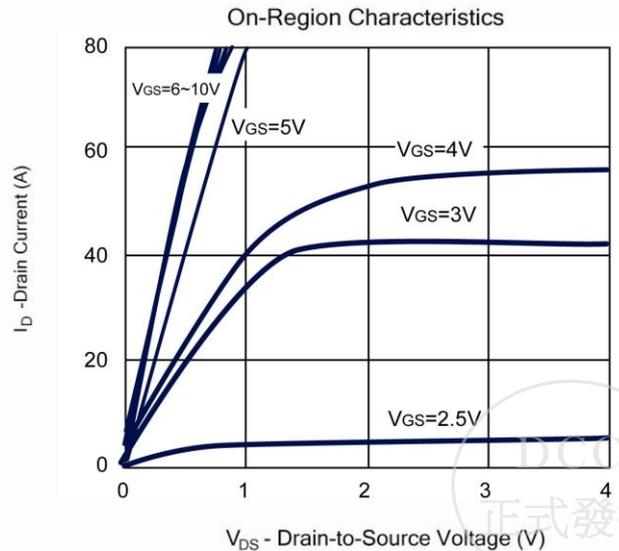
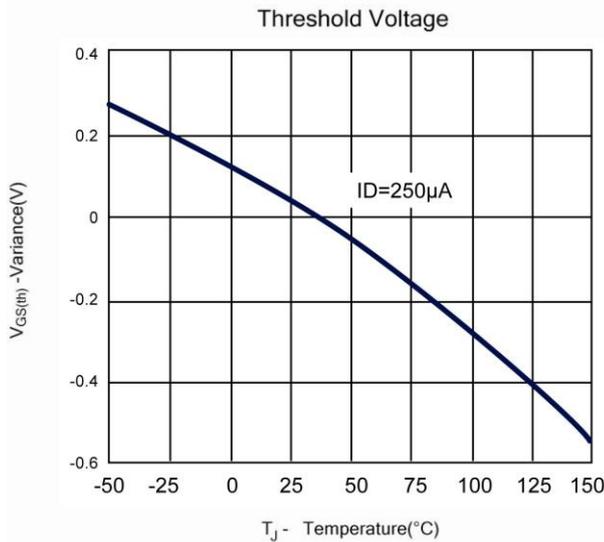
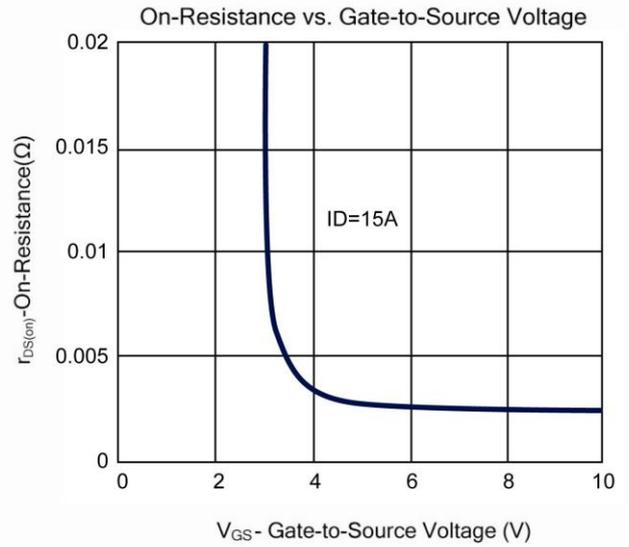
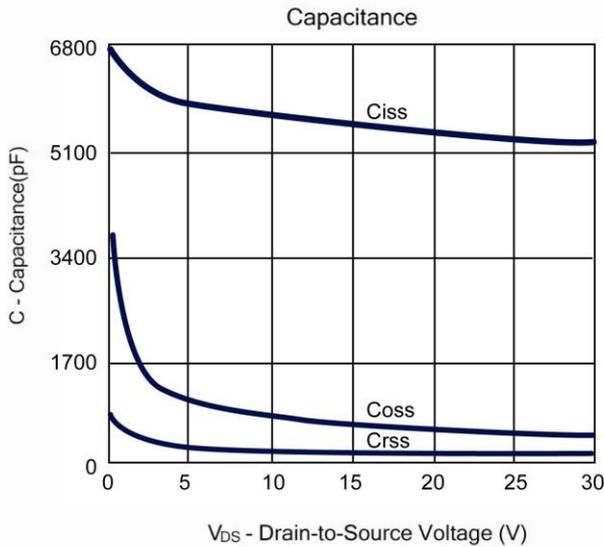
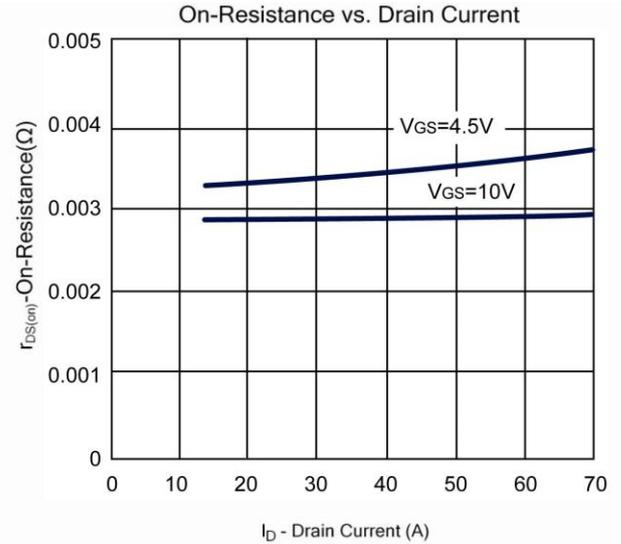
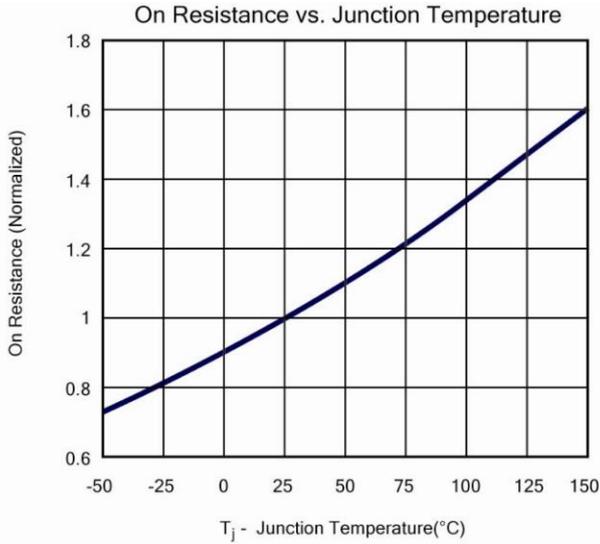
Notes: a. Pulse test: pulse width ≤ 300us, duty cycle ≤ 2%, Guaranteed by design, not subject to production testing.

b. Matsuki reserves the right to improve product design, functions and reliability without notice.



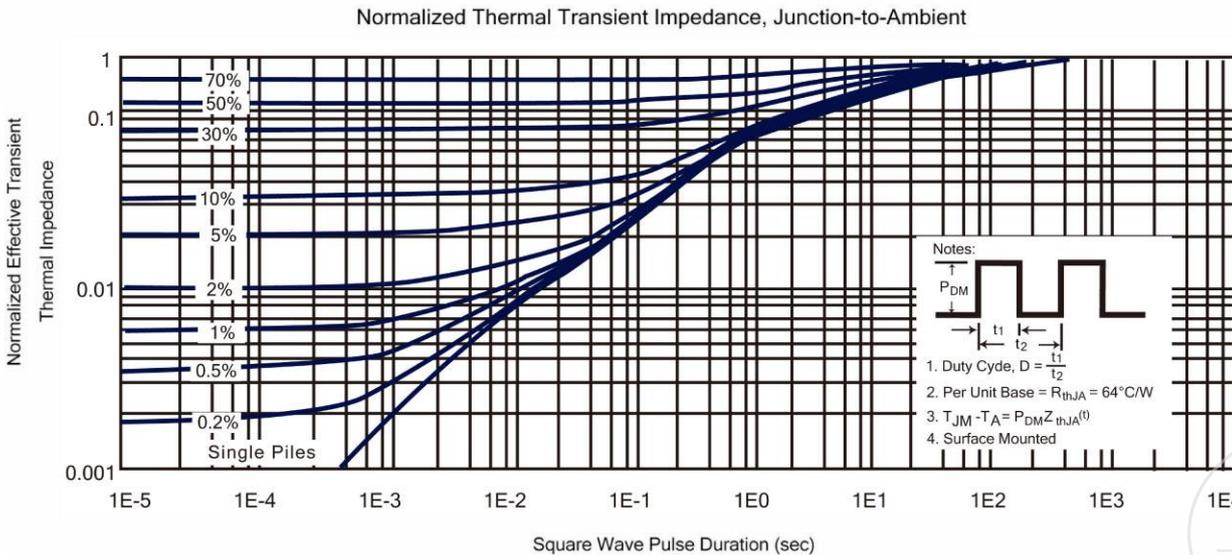
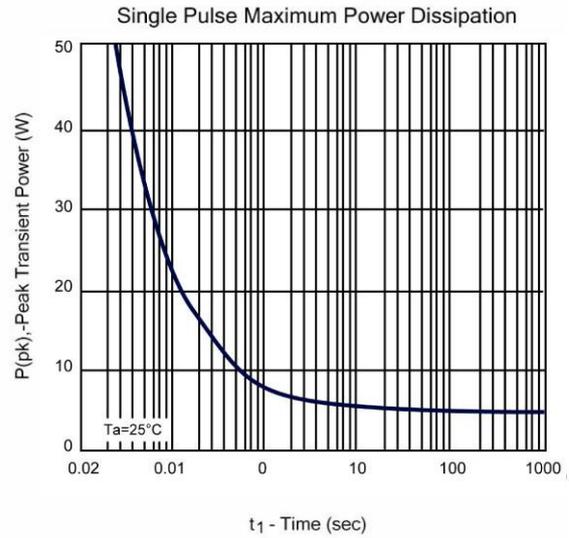
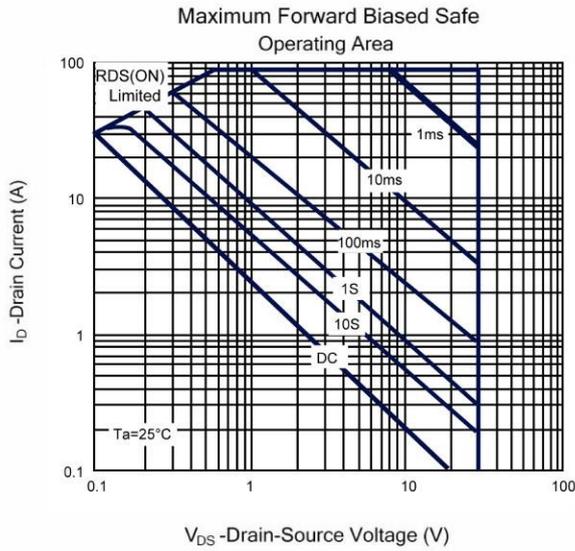
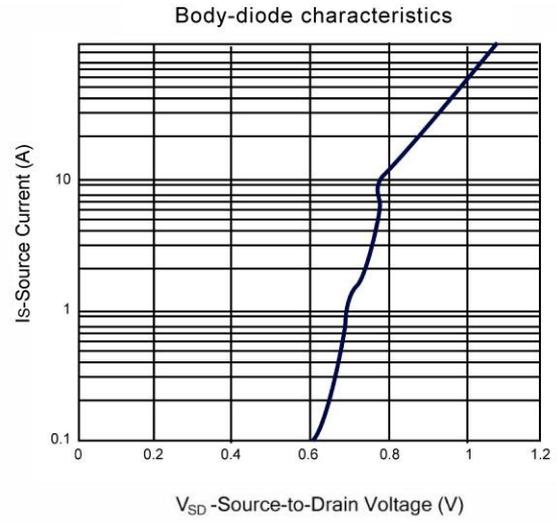
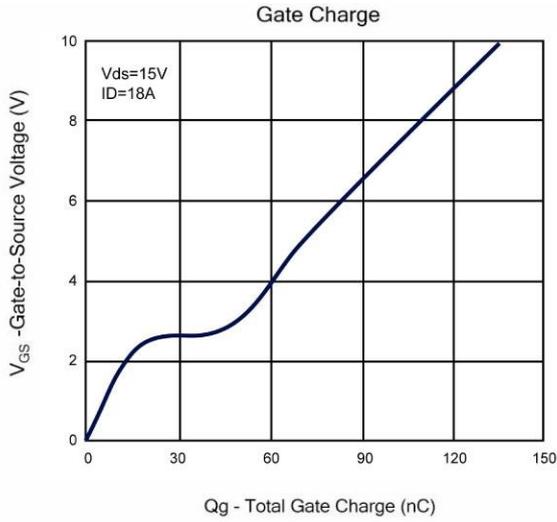
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Typical Characteristics (T_J =25°C Noted)

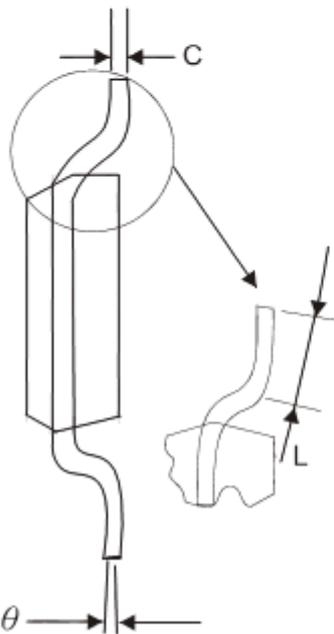
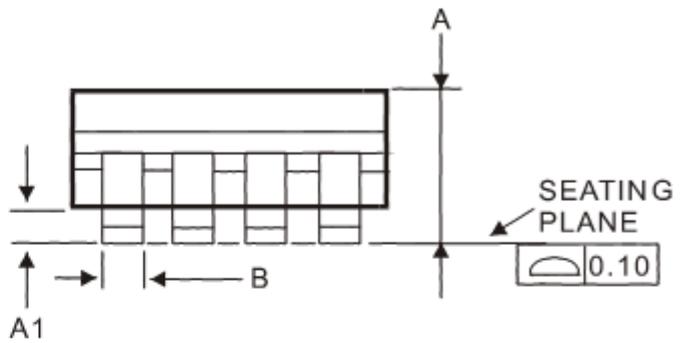
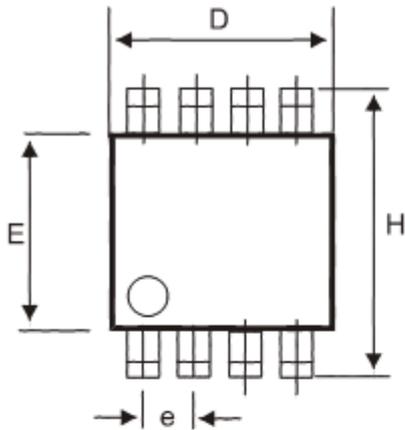


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Typical Characteristics (T_J =25°C Noted)



SOP-8 Package Outline



DIM	MILLIMETERS (mm)	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
L	0.40	1.25
θ	0°	7°

Note: 1. Refer to JEDEC MS-012AA.

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per side.

